INTEGRATED CIRCUITS

DATA SHEET

74ALVC14
Hex inverting Schmitt trigger

Product specification   2003 Feb 03

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Hex inverting Schmitt trigger | 74ALVC14

FEATURES

- Wide supply voltage range from 1.65 to 3.6 V
- Complies with JEDEC standard:
  JESD8-7 (1.65 to 1.95 V)
  JESD8-5 (2.3 to 2.7 V)
  JESD8B/JESD36 (2.7 to 3.6 V).
- 3.6 V tolerant inputs/outputs
- CMOS low power consumption
- Direct interface with TTL levels (2.7 to 3.6 V)
- Power-down mode
- Unlimited input rise and fall times
- Latch-up performance exceeds 250 mA
- ESD protection:
  HBM EIA/JESD22-A114-A exceeds 2000 V
  MM EIA/JESD22-A115-A exceeds 200 V.

DESCRIPTION

The 74ALVC14 is a high-performance, low-power, low-voltage, Si-gate CMOS device and superior to most advanced CMOS compatible TTL families.

The 74ALVC14 provides six inverting buffers with Schmitt-trigger action. It is capable of transforming slowly changing input signals into sharply defined, jitter-free output signals.

QUICK REFERENCE DATA

GND = 0 V; T_{amb} = 25 °C.

SYMBOL	PARAMETER	CONDITIONS	TYPICAL	UNIT
t_{PHL}/t_{PLH}	propagation delay input nA to output nY	V_{CC} = 1.8 V; C_L = 30 pF; R_L = 1 kΩ	2.9	ns
		V_{CC} = 2.5 V; C_L = 30 pF; R_L = 500 Ω	2.2	ns
		V_{CC} = 2.7 V; C_L = 50 pF; R_L = 500 Ω	2.8	ns
		V_{CC} = 3.3 V; C_L = 50 pF; R_L = 500 Ω	2.4	ns
C_I	input capacitance		3.5	pF
C_{PD}	power dissipation capacitance per buffer	V_{CC} = 3.3 V; notes 1 and 2	25	pF

Notes

1. C_{PD} is used to determine the dynamic power dissipation (P_D in μW).

   $P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o)$ where:

   f_i = input frequency in MHz;

   f_o = output frequency in MHz;

   C_L = output load capacitance in pF;

   V_{CC} = supply voltage in Volts;

   N = total switching outputs;

   $\Sigma(C_L \times V_{CC}^2 \times f_o)$ = sum of the outputs.

2. The condition is V_I = GND to V_{CC}.

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ORDERING INFORMATION

TYPE NUMBER	PACKAGE			
	PINS	**PACKAGE**	**MATERIAL**	**CODE**
74ALVC14D	14	SO14	plastic	SOT108-1
74ALVC14PW	14	TSSOP14	plastic	SOT402-1

FUNCTION TABLE

See note 1.

INPUT	OUTPUT
nA	**nY**
L	H
H	L

Note

1. H = HIGH voltage level;

   L = LOW voltage level.

PINNING

PIN	SYMBOL	DESCRIPTION
1	1A	data input
2	1Y	data output
3	2A	data input
4	2Y	data output
5	3A	data input
6	3Y	data output
7	GND	ground (0 V)
8	4Y	data output
9	4A	data input
10	5Y	data output
11	5A	data input
12	6Y	data output
13	6A	data input
14	V_{CC}	supply voltage

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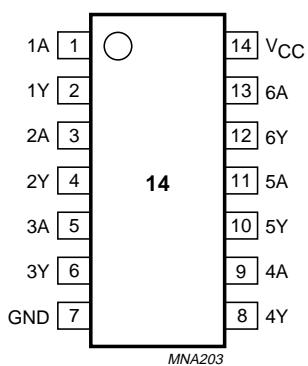
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Fig.1 Pin configuration.
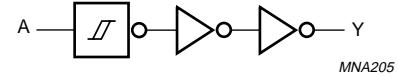
Fig.2 Logic diagram (one Schmitt-trigger).
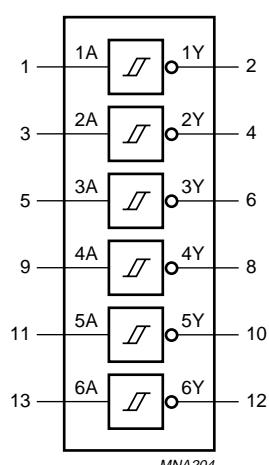
Fig.3 Logic symbol.

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RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CC}	supply voltage		1.65	3.6	V
V_I	input voltage		0	3.6	V
V_O	output voltage	V_{CC} = 1.65 to 3.6 V	0	V_{CC}	V
		V_{CC} = 0 V; Power-down mode	0	3.6	V
T_{amb}	operating ambient temperature		−40	+85	°C
t_r, t_f	input rise and fall times	V_{CC} = 1.65 to 2.7 V	0	20	ns/V
		V_{CC} = 2.7 to 3.6 V	0	10	ns/V

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134); voltages are referenced to GND (ground = 0 V).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CC}	supply voltage		−0.5	+4.6	V
I_{IK}	input diode current	V_I < 0	–	−50	mA
V_I	input voltage		−0.5	+4.6	V
I_{OK}	output diode current	V_O > V_{CC} or V_O < 0	–	±50	mA
V_O	output voltage	notes 1 and 2	−0.5	V_{CC} + 0.5	V
		Power-down mode; note 2	−0.5	+4.6	V
I_O	output source or sink current	V_O = 0 to V_{CC}	–	±50	mA
I_{CC}, I_{GND}	V_{CC} or GND current		–	±100	mA
T_{stg}	storage temperature		−65	+150	°C
P_{tot}	power dissipation				
	SO package	above 70 °C derate linearly with 8 mW/K	–	500	mW
	TSSOP package	above 60 °C derate linearly with 5.5 mW/K	–	500	mW

Notes

1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. When V_{CC} = 0 V (Power-down mode), the output voltage can be 3.6 V in normal operation.

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DC CHARACTERISTICS

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

SYMBOL	PARAMETER	TEST CONDITIONS		MIN.	TYP.[1]	MAX.	UNIT
		OTHER	V_{CC} (V)				
T_{amb} = −40 to +85 °C							
V_{OL}	LOW-level output voltage	$V_I = V_{IH}$ or V_{IL}					
		I_O = 100 µA	1.65 to 3.6	–	–	0.2	V
		I_O = 6 mA	1.65	–	0.11	0.3	V
		I_O = 12 mA	2.3	–	0.17	0.4	V
		I_O = 18 mA	2.3	–	0.25	0.6	V
		I_O = 12 mA	2.7	–	0.16	0.4	V
		I_O = 18 mA	3.0	–	0.23	0.4	V
		I_O = 24 mA	3.0	–	0.30	0.55	V
V_{OH}	HIGH-level output voltage	$V_I = V_{IH}$ or V_{IL}					
		I_O = −100 µA	1.65 to 3.6	V_{CC} − 0.2	–	–	V
		I_O = −6 mA	1.65	1.25	1.51	–	V
		I_O = −12 mA	2.3	1.8	2.10	–	V
		I_O = −18 mA	2.3	1.7	2.01	–	V
		I_O = −12 mA	2.7	2.2	2.53	–	V
		I_O = −18 mA	3.0	2.4	2.76	–	V
		I_O = −24 mA	3.0	2.2	2.68	–	V
I_{LI}	input leakage current	V_I = 3.6 V or GND	3.6	–	±0.1	±5	µA
I_{off}	power OFF leakage current	V_I or V_O = 3.6 V	0.0	–	±0.1	±10	µA
I_{CC}	quiescent supply current	$V_I = V_{CC}$ or GND; I_O = 0	3.6	–	0.2	10	µA
ΔI_{CC}	additional quiescent supply current per input pin	$V_I = V_{CC}$ − 0.6 V; I_O = 0	3.0 to 3.6	–	5	750	µA

Note

1. All typical values are measured at T_{amb} = 25 °C.

TRANSFER CHARACTERISTICS

Voltage are referenced to GND (ground = 0 V).

| SYMBOL	PARAMETER	TEST CONDITIONS		MIN.	TYP.[1]	MAX.	UNIT
		WAVEFORMS	V_{CC} (V)				
T_{amb} = −40 to +85 °C							
V_{T+}	positive-going threshold	see Figs 4 and 5	1.65	0.7	0.98	1.24	V
			1.95	0.75	1.12	1.46	V
			2.3	0.9	1.27	1.7	V
			2.7	1.0	1.43	2.0	V
			3.0	1.1	1.56	2.0	V
			3.6	1.1	1.81	2.0	V
V_{T-}	negative-going threshold	see Figs 4 and 5	1.65	0.41	0.64	0.9	V
			1.95	0.49	0.76	1.1	V
			2.3	0.6	0.90	1.3	V
			2.7	0.7	1.06	1.4	V
			3.0	0.8	1.19	1.5	V
			3.6	0.8	1.42	1.7	V
V_H	hysteresis ($V_{T+} - V_{T-}$)	see Figs 4 and 5	1.65	0.25	0.34	0.62	V
			1.95	0.25	0.36	0.62	V
			2.3	0.3	0.36	1.0	V
			2.7	0.3	0.38	1.1	V
			3.0	0.3	0.37	1.2	V
			3.6	0.3	0.40	1.2	V

Notes

1. All typical values are measured at T_{amb} = 25 °C.

2. The V_{IH} and V_{IL} from the DC family characteristics are superseded by the V_{T+} and V_{T-}.
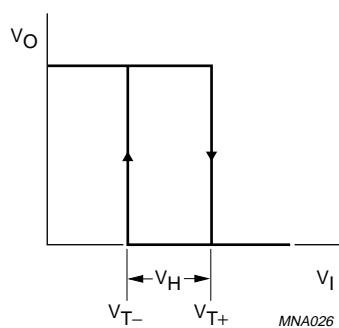
Fig.4 Transfer characteristic.
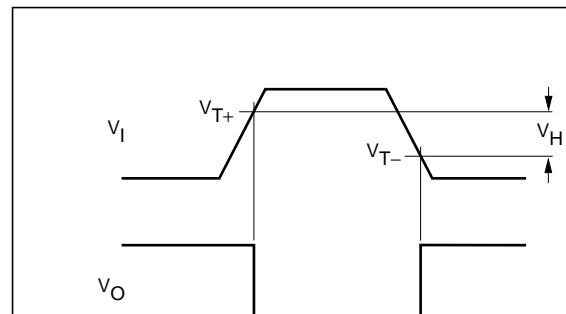
Where V_{T+} and V_{T-} are between limits of 20% and 70%.

Fig.5 Definition of V_{T+}, V_{T-} and V_H

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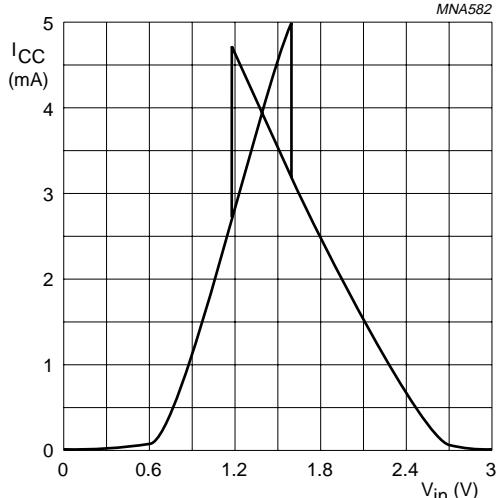
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Fig.6 Typical 74ALVC14 transfer characteristic

V_{CC} = 3.0 V.

AC CHARACTERISTICS

SYMBOL	PARAMETER	TEST CONDITIONS		MIN.	TYP.[1]	MAX.	UNIT
		WAVEFORMS	V_{CC} (V)				
T_{amb} = −40 to +85 °C							
t_{PHL}/t_{PLH}	propagation delay nA to nY	see Figs 7 and 8	1.65 to 1.95	1.0	2.9	4.4	ns
			2.3 to 2.7	1.0	2.2	3.7	ns
			2.7	1.0	2.8	3.9	ns
			3.0 to 3.6	1.0	2.4	3.4	ns

Note

1. All typical values are measured at T_{amb} = 25 °C.

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AC WAVEFORMS
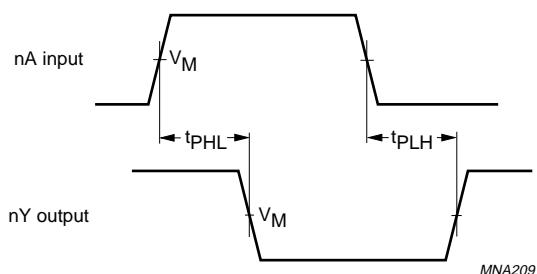
V$_{CC}$	V$_M$	INPUT	
		V$_I$	t$_r$ = t$_f$
1.65 to 1.95 V	0.5 × V$_{CC}$	V$_{CC}$	≤ 2.0 ns
2.3 to 2.7 V	0.5 × V$_{CC}$	V$_{CC}$	≤ 2.0 ns
2.7 V	1.5 V	2.7 V	≤ 2.5 ns
3.0 to 3.6 V	1.5 V	2.7 V	≤ 2.5 ns

Fig.7 Input nA to output nY propagation delay times.
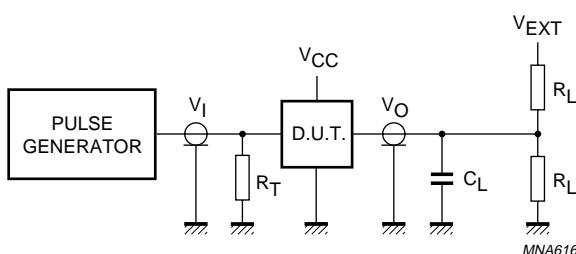
| V$_{CC}$	V$_I$	C$_L$	R$_L$	V$_{EXT}$		
				t$_{PLH}$/t$_{PHL}$	t$_{PZH}$/t$_{PHZ}$	t$_{PZL}$/t$_{PLZ}$
1.65 to 1.95 V	V$_{CC}$	30 pF	1 kΩ	open	GND	2 × V$_{CC}$
2.3 to 2.7 V	V$_{CC}$	30 pF	500 Ω	open	GND	2 × V$_{CC}$
2.7 V	2.7 V	50 pF	500 Ω	open	GND	6 V
3.0 to 3.6 V	2.7 V	50 pF	500 Ω	open	GND	6 V

R$_L$ = Load resistor.

C$_L$ = Load capacitance including jig and probe capacitance.

R$_T$ = Termination resistance should be equal to the output impedance Z$_o$ of the pulse generator.

Fig.8 Load circuitry for switching times.

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APPLICATION INFORMATION
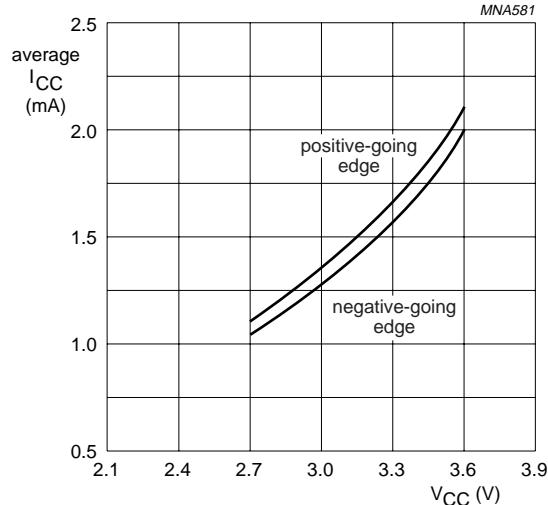
Linear change of VI between 0.8 to 2.0 V.
All values given are typical unless otherwise specified.

Fig.9　Average I_{CC} for ALVC Schmitt-trigger devices.

$$f = \frac{1}{T} \approx \frac{1}{0.8 \times RC} \qquad V_{CC} = 3.0 \text{ V.}$$
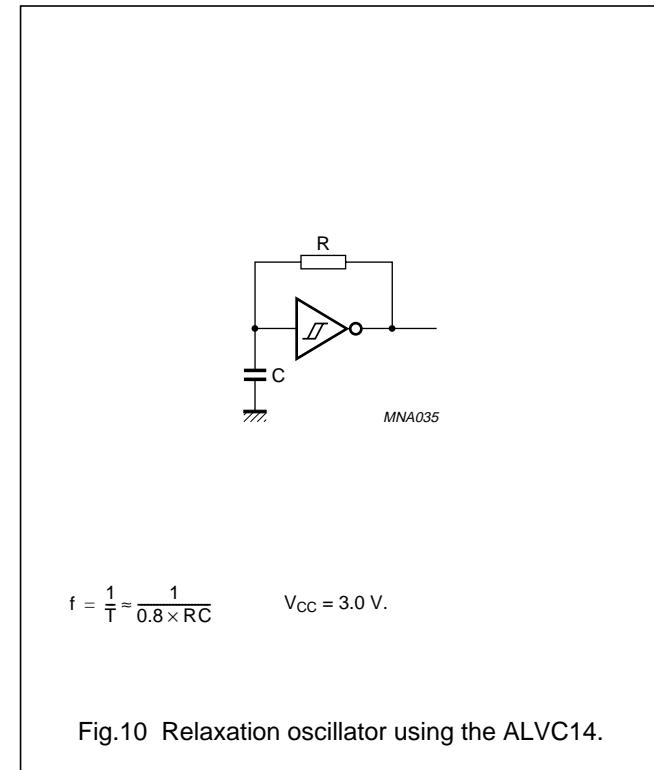
Fig.10　Relaxation oscillator using the ALVC14.

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PACKAGE OUTLINES

**SO14: plastic small outline package; 14 leads; body width 3.9 mm**   **SOT108-1**


0   2.5   5 mm

scale
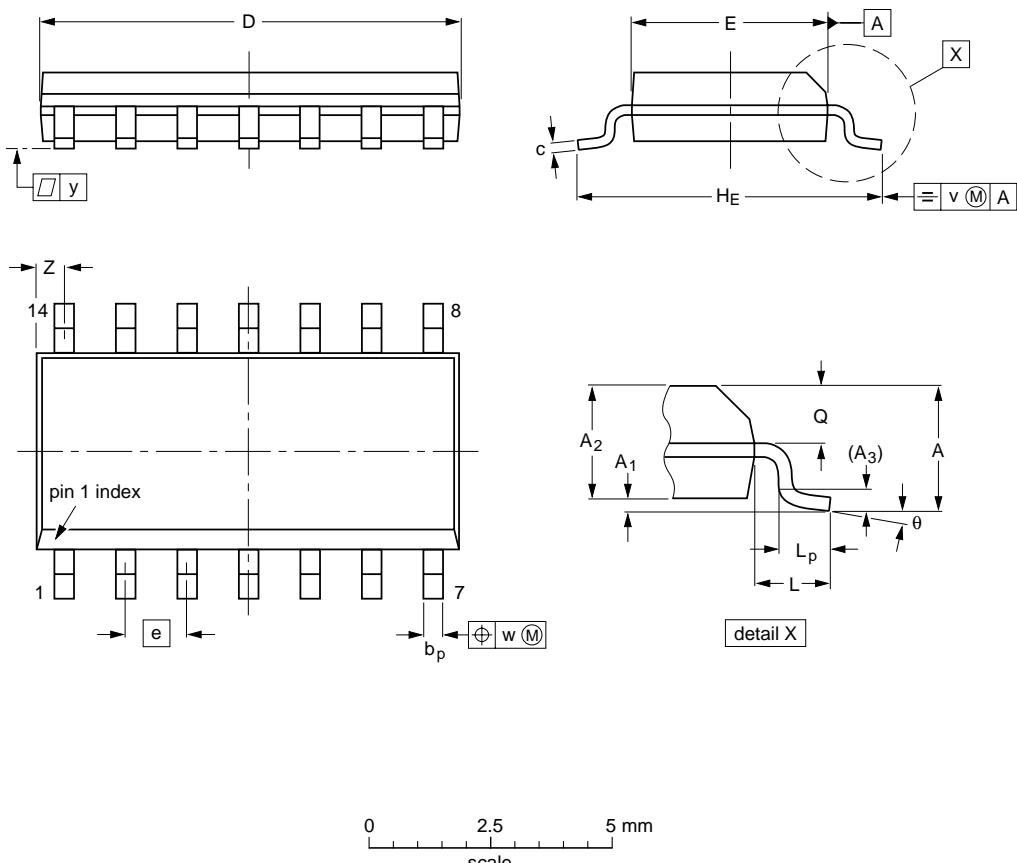
DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A₁	A₂	A₃	b_p	c	D(1)	E(1)	e	H_E	L	L_p	Q	v	w	y	Z(1)	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	8.75 8.55	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8° 0°
inches	0.069	0.010 0.004	0.057 0.049	0.01	0.019 0.014	0.0100 0.0075	0.35 0.34	0.16 0.15	0.050	0.244 0.228	0.041	0.039 0.016	0.028 0.024	0.01	0.01	0.004	0.028 0.012	

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT108-1	076E06	MS-012				~~97-05-22~~ 99-12-27

TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm **SOT402-1**

detail X
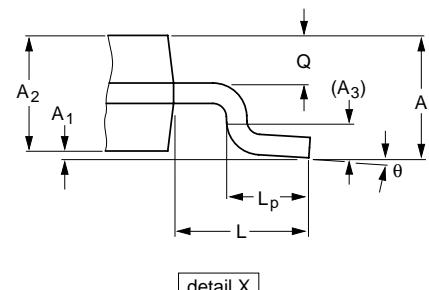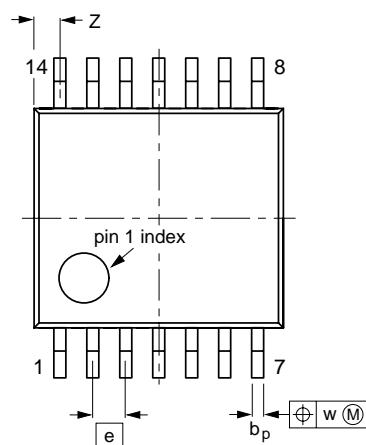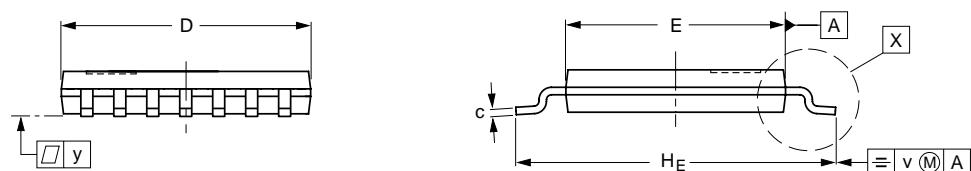
```
0        2.5        5 mm
scale
```

DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(2)}$	e	H_E	L	L_p	Q	v	w	y	$Z^{(1)}$	θ
mm	1.10	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	5.1 4.9	4.5 4.3	0.65	6.6 6.2	1.0	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.72 0.38	8° 0°

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT402-1		MO-153				~~95-04-04~~ 99-12-27

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SOLDERING

Introduction to soldering surface mount packages

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our *"Data Handbook IC26; Integrated Circuit Packages"* (document order number 9398 652 90011).

There is no soldering method that is ideal for all surface mount IC packages. Wave soldering can still be used for certain surface mount ICs, but it is not suitable for fine pitch SMDs. In these situations reflow soldering is recommended.

Reflow soldering

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement.

Several methods exist for reflowing; for example, convection or convection/infrared heating in a conveyor type oven. Throughput times (preheating, soldering and cooling) vary between 100 and 200 seconds depending on heating method.

Typical reflow peak temperatures range from 215 to 250 °C. The top-surface temperature of the packages should preferable be kept below 220 °C for thick/large packages, and below 235 °C for small/thin packages.

Wave soldering

Conventional single wave soldering is not recommended for surface mount devices (SMDs) or printed-circuit boards with a high component density, as solder bridging and non-wetting can present major problems.

To overcome these problems the double-wave soldering method was specifically developed.

If wave soldering is used the following conditions must be observed for optimal results:

- Use a double-wave soldering method comprising a turbulent wave with high upward pressure followed by a smooth laminar wave.
- For packages with leads on two sides and a pitch (e):
  - larger than or equal to 1.27 mm, the footprint longitudinal axis is **preferred** to be parallel to the transport direction of the printed-circuit board;
  - smaller than 1.27 mm, the footprint longitudinal axis **must** be parallel to the transport direction of the printed-circuit board.

  The footprint must incorporate solder thieves at the downstream end.

- For packages with leads on four sides, the footprint must be placed at a 45° angle to the transport direction of the printed-circuit board. The footprint must incorporate solder thieves downstream and at the side corners.

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Typical dwell time is 4 seconds at 250 °C.
A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

Manual soldering

Fix the component by first soldering two diagonally-opposite end leads. Use a low voltage (24 V or less) soldering iron applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to 300 °C.

When using a dedicated tool, all other leads can be soldered in one operation within 2 to 5 seconds between 270 and 320 °C.

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Suitability of surface mount IC packages for wave and reflow soldering methods

PACKAGE[1]	SOLDERING METHOD	
	WAVE	**REFLOW**[2]
BGA, LBGA, LFBGA, SQFP, TFBGA, VFBGA	not suitable	suitable
DHVQFN, HBCC, HBGA, HLQFP, HSQFP, HSOP, HTQFP, HTSSOP, HVQFN, HVSON, SMS	not suitable[3]	suitable
PLCC[4], SO, SOJ	suitable	suitable
LQFP, QFP, TQFP	not recommended[4][5]	suitable
SSOP, TSSOP, VSO, VSSOP	not recommended[6]	suitable

Notes

1. For more detailed information on the BGA packages refer to the *"(LF)BGA Application Note"* (AN01026); order a copy from your Philips Semiconductors sales office.

2. All surface mount (SMD) packages are moisture sensitive. Depending upon the moisture content, the maximum temperature (with respect to time) and body size of the package, there is a risk that internal or external package cracks may occur due to vaporization of the moisture in them (the so called popcorn effect). For details, refer to the *Drypack information* in the *"Data Handbook IC26; Integrated Circuit Packages; Section: Packing Methods"*.

3. These packages are not suitable for wave soldering. On versions with the heatsink on the bottom side, the solder cannot penetrate between the printed-circuit board and the heatsink. On versions with the heatsink on the top side, the solder might be deposited on the heatsink surface.

4. If wave soldering is considered, then the package must be placed at a 45° angle to the solder wave direction. The package footprint must incorporate solder thieves downstream and at the side corners.

5. Wave soldering is suitable for LQFP, TQFP and QFP packages with a pitch (e) larger than 0.8 mm; it is definitely not suitable for packages with a pitch (e) equal to or smaller than 0.65 mm.

6. Wave soldering is suitable for SSOP and TSSOP packages with a pitch (e) equal to or larger than 0.65 mm; it is definitely not suitable for packages with a pitch (e) equal to or smaller than 0.5 mm.

DATA SHEET STATUS

LEVEL	DATA SHEET STATUS[1]	PRODUCT STATUS[2][3]	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
II	Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
III	Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Relevant changes will be communicated via a Customer Product/Process Change Notification (CPCN).

Notes

1. Please consult the most recently issued data sheet before initiating or completing a design.

2. The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.

3. For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

DEFINITIONS

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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